

WHAT IS CLAIMED IS:

1. A trimming method of an electric circuit board including a glass substrate, and an electric circuit constituting element on or inside the glass substrate, said method comprising steps of

focusing an electromagnetic wave onto said predetermined electric circuit constituting element inside or on said glass substrate through said glass substrate; and

adjusting an electric property of said predetermined electric circuit constituting element positioned in the vicinity of a focus of said electromagnetic wave.

2. A trimming method of an electric circuit board including a glass substrate, an electric circuit constituting element inside the glass substrate, and a pair of electrodes disposed so as to hold the electric circuit constituting element therebetween, said method comprising steps of

focusing a laser beam emitted from a laser light source onto said predetermined electric circuit constituting element inside said glass substrate through said glass substrate in such a manner that said electrodes are avoided; and

adjusting an electric property of said predetermined electric circuit constituting element by irradiation with the laser beam for a short time.

3. A trimming method of an electric circuit

board including a glass substrate, and an electric circuit constituting element inside the glass substrate, said method comprising steps of

    focusing a laser beam emitted from a laser light source onto a dielectric disposed or to be disposed in said glass substrate through said glass substrate;

    changing a state of said dielectric by irradiation with the laser beam for a short time and

    adjusting an electric property of the predetermined electric circuit constituting element.

4.       The trimming method of the electric circuit board including the glass substrate according to claim 1, comprising a step of forming a crystal grain and/or a crystal rod in said glass substrate by irradiation with said electromagnetic wave or the laser beam.

5.       The trimming method of the electric circuit board including the glass substrate according to claim 1, comprising a step of partially changing a state of a dielectric disposed and/or to be disposed in said glass substrate and adjusting an electric capacity.

6.       The trimming method of the electric circuit board including the glass substrate according to claim 1, comprising a step of partially cutting a wiring disposed in said glass substrate and adjusting the electric property.

7.       The trimming method of the electric circuit board including the glass substrate according to claim

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1, comprising a step of partially removing or cutting an electrode of an electric capacity disposed in said glass substrate and adjusting the electric property.

8. An electric circuit board including a glass substrate, comprising:

the glass substrate;

a wiring formed on a main surface and/or a back surface of the glass substrate; a plurality of external connection terminals electrically connected to the wiring;

and an external electric component connected to the external connection terminals,

wherein a state change portion is partially disposed inside said glass substrate.

9. An electric circuit board including a glass substrate, comprising:

the glass substrate;

a wiring formed on a main surface and/or a back surface of said glass substrate; a through hole and/or an end-surface wiring for electrically connecting the wiring formed on the main surface of said glass substrate to the main surface and the back surface of the glass substrate;

a plurality of external connection terminals formed on the back surface of said glass substrate and electrically connected to the wiring disposed on said main surface; and

an external component connected to some of

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glass substrate;

a process of forming a trimmable passive component;

a process of forming another passive component;

a process of mounting another component;

a process of measuring an electric property of a mounted circuit board;

a process of calculating a trimming amount from a measured value; and

a process of focusing on and irradiating the inside of the glass substrate with an electromagnetic wave based on the calculated trimming amount and subjecting a part of the inside of the glass substrate to state change.

15. A trimming apparatus of an electric circuit board including a glass substrate, comprising:

means for measuring an electric property of a mounted circuit board;

means for calculating a trimming amount from a measured value;

means for focusing on and irradiating the inside of the glass substrate with an electromagnetic wave based on the calculated trimming amount and partially trimming the inside of the glass substrate; and

means for managing information of said measured value and said trimming amount.